

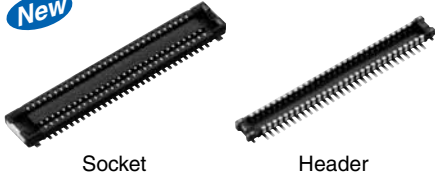
The world's smallest size* contributes to the miniaturization and functionality enhancement of target equipment.

NARROW PITCH (0.35 mm) CONNECTORS ADVANCED SERIES A35S

* As of March 2009, among mass-produced models (based on our company research)



New



Socket

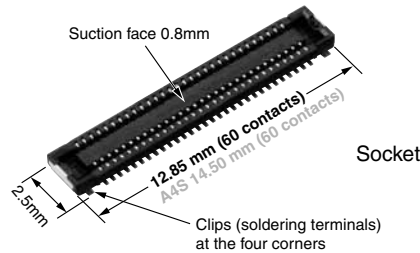
Header

Compliance with RoHS Directive

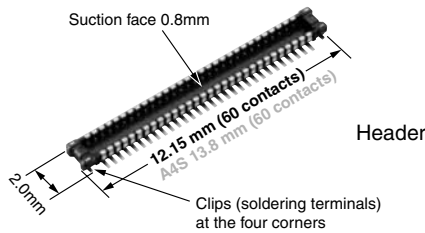
FEATURES

1. The world's smallest size* (width: 2.5 mm, Terminal pitch: 0.35 mm and Mated height: 0.8 mm)

The footprint when mated is down approx. 10% from our existing A4S model (60 contacts), contributing to the functionality enhancement and size reduction of target equipment.

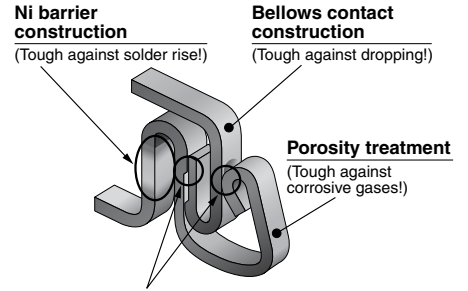


Socket



Header

2. "TOUGH CONTACT ADVANCED" structure adopted to ensure high resistance to various environments in spite of the ultra-slim space-saving body.



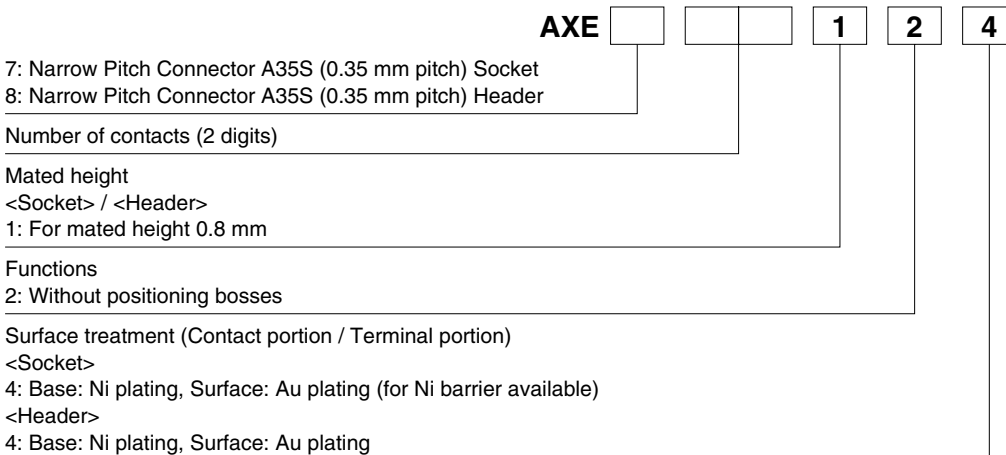
V notch and Double contact constructions (Tough against foreign particles and flux!)

3. The world's first* low-profile connector with up to 120 contacts
4. The clips (soldering terminals) at the four corners enhance the mounting strength.
5. The simple lock structure for good mating/unmating operation feel.
6. The gull-wing-shaped terminals facilitate imaging inspections.

APPLICATIONS

- Particularly suitable for board-to-FPC connections in ultra-compact mobile equipment that requires size and thickness reduction and functionality enhancement

ORDERING INFORMATION



PRODUCT TYPES

Mated height	Number of contacts	Part number		Packing	
		Socket	Header	Inner carton	Outer carton
0.8mm	60	AXE760124	AXE860124	5,000 pieces	10,000 pieces
	120	AXE7A2124	AXE8A2124		

Notes: 1. Order unit:

For mass production: in 1-inner-box (1-reel) units

Samples for mounting check: in 50-connector units. Please contact our sales office.

2. The above part numbers are for connectors without positioning bosses, which are standard. When ordering connectors with positioning bosses, please contact our sales office.

3. Please contact us for connectors having a number of contacts other than those listed above.

SPECIFICATIONS

1. Characteristics

	Item	Specifications	Conditions
Electrical characteristics	Rated current	0.25A/contact (Max. 4 A at total contacts)	
	Rated voltage	60V AC/DC	
	Breakdown voltage	150V AC for 1 min.	No short-circuiting or damage at a detection current of 1 mA when the specified voltage is applied for one minute.
	Insulation resistance	Min. 1,000M Ω (initial)	Using 250V DC megger (applied for 1 min.)
Mechanical characteristics	Contact resistance	Max. 100m Ω	Based on the contact resistance measurement method specified by JIS C 5402.
	Composite insertion force	Max. 0.981N/contacts \times contacts (initial)	
	Composite removal force	Min. 0.165N/contacts \times contacts	
Environmental characteristics	Contact holding force (Socket contact)	Min. 0.20N/contacts	Measuring the maximum force. As the contact is axially pull out.
	Ambient temperature	-55°C to +85°C	No freezing at low temperatures. No dew condensation.
	Soldering heat resistance	Peak temperature: 260°C or less (on the surface of the PC board around the connector terminals)	Infrared reflow soldering
		300°C within 5 sec. 350°C within 3 sec.	Soldering iron
	Storage temperature	-55°C to +85°C (product only) -40°C to +50°C (emboss packing)	No freezing at low temperatures. No dew condensation.
	Thermal shock resistance (header and socket mated)	5 cycles, insulation resistance min. 100M Ω , contact resistance max. 100m Ω	Sequence 1. -55 $\frac{3}{5}$ °C, 30 minutes 2. ~, Max. 5 minutes 3. 85 $\frac{3}{5}$ °C, 30 minutes 4. ~, Max. 5 minutes
	Humidity resistance (header and socket mated)	120 hours, insulation resistance min. 100M Ω , contact resistance max. 100m Ω	Bath temperature 40 \pm 2°C, humidity 90 to 95% R.H.
Saltwater spray resistance (header and socket mated)	24 hours, insulation resistance min. 100M Ω , contact resistance max. 100m Ω	Bath temperature 35 \pm 2°C, saltwater concentration 5 \pm 1%	
H ₂ S resistance (header and socket mated)	48 hours, contact resistance max. 100m Ω	Bath temperature 40 \pm 2°C, gas concentration 3 \pm 1 ppm, humidity 75 to 80% R.H.	
Lifetime characteristics	Insertion and removal life	30 times	Repeated insertion and removal speed of max. 200 times/ hours
Unit weight		60 contact type: Socket: 0.03 g Header: 0.01 g	

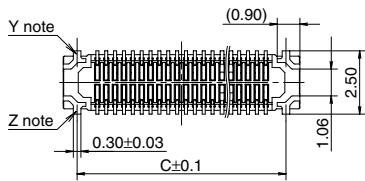
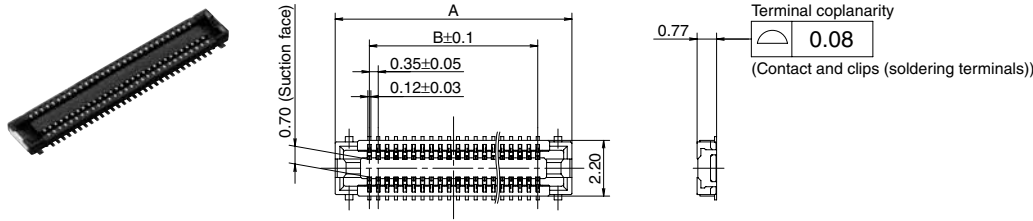
2. Material and surface treatment

Part name	Material	Surface treatment
Molded portion	LCP resin (UL94V-0)	—
Contact and Post	Copper alloy	Contact portion: Base: Ni plating, Surface: Au plating Terminal portion: Base: Ni plating, Surface: Au plating (except the terminal tips) The socket terminals close to the portion to be soldered have nickel barriers (exposed nickel portions). Clips (soldering terminals): Sockets: Base: Ni plating, Surface: Pd+Au flash plating (except the terminal tips) Headers: Base: Ni plating, Surface: Au plating (except the terminal tips)

AXE7, 8

DIMENSIONS (Unit: mm)

Socket (Mated height: 0.8 mm)



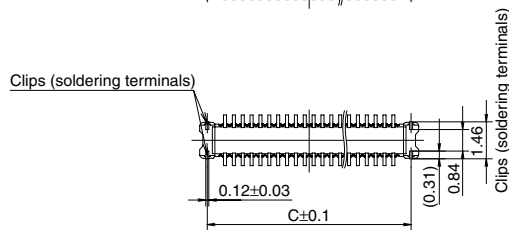
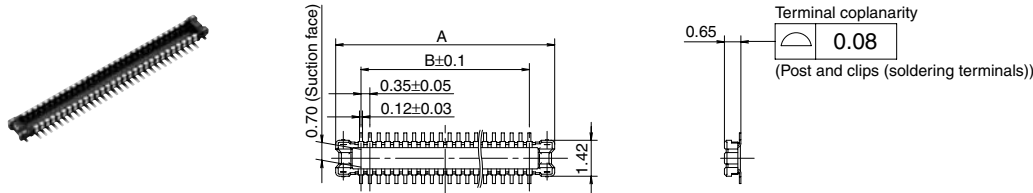
Dimension table (mm)

Number of contacts/ dimension	A	B	C
60	12.85	10.15	11.75
120	23.35	20.65	22.25

General tolerance: ± 0.2

Note: Since the clips (soldering terminal) has a single-piece construction, sections Y and Z are electrically connected.

Header (Mated height: 1.0 mm)

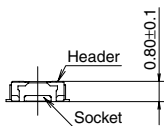


Dimension table (mm)

Number of contacts/ dimension	A	B	C
60	12.12	10.15	11.55
120	22.65	20.65	22.05

General tolerance: ± 0.2

• Socket and Header are mated



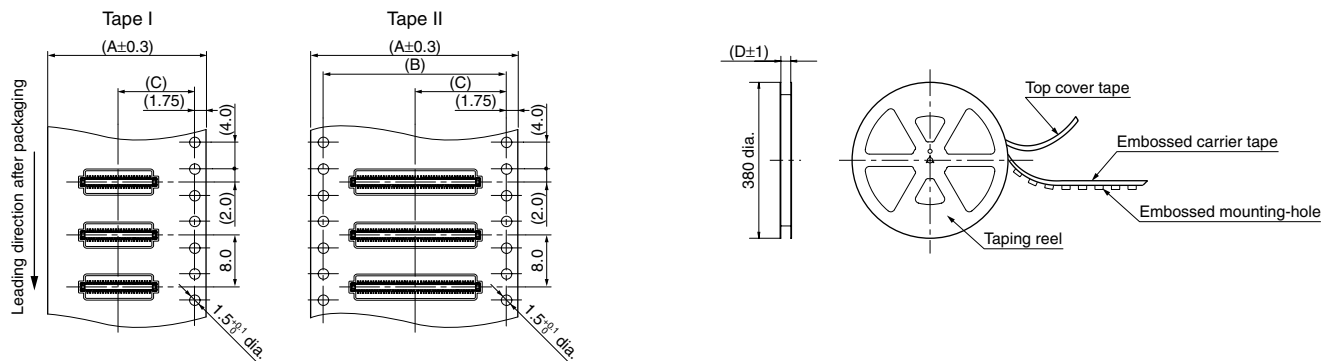
EMBOSSED TAPE DIMENSIONS (Unit: mm) (Common to all sockets and headers)

• Specifications for taping

(In accordance with JIS C 0806-1990. However, not applied to the mounting-hole pitch of some connectors.)

• Specifications for the plastic reel

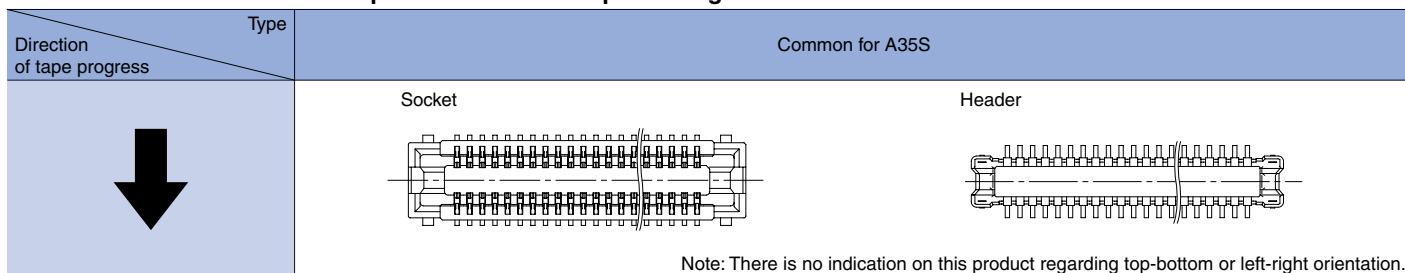
(In accordance with EIAJET-7200B.)



• Dimension table (Unit: mm)

Type/Mated height	Number of contacts	Type of taping	A	B	C	D	Quantity per reel
Common for sockets and headers: 0.8mm	60	Tape I	24.0	—	11.5	25.4	5,000
	120	Tape II	44.0	40.4	20.2	45.4	5,000

• Connector orientation with respect to embossed tape feeding direction



Note: There is no indication on this product regarding top-bottom or left-right orientation.

NOTES

■ Regarding the design of PC board patterns

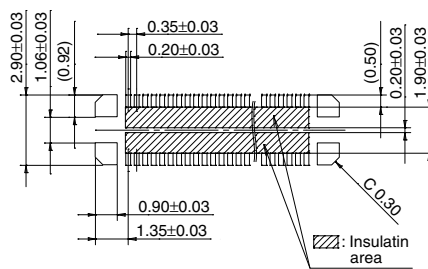
Conduct the recommended foot pattern design, in order to preserve the mechanical strength of terminal solder areas.

■ Recommended PC board and metal mask patterns

Appropriate control of solder amount is required to minimize solder bridges and other defects for connectors with 0.35-mm, 0.4-mm or 0.5-mm pitch terminals, which require high-density mounting. Refer to the right-hand drawing for recommended patterns.

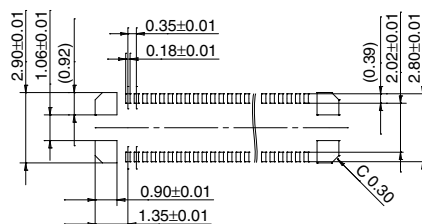
• Socket (Mated height: 0.8 mm)

Recommended PC board pattern (TOP VIEW)



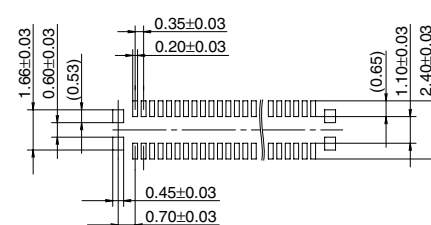
Recommended metal mask opening pattern

Metal mask thickness: When $120 \mu\text{m}$
(Terminal opening ratio: 70%)
(Metal-part opening ratio: 100%)



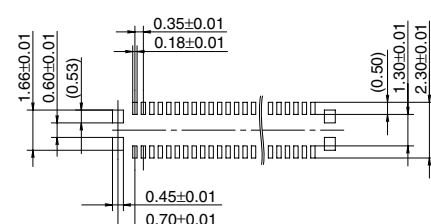
• Header (Mated height: 0.8 mm)

Recommended PC board pattern (TOP VIEW)



Recommended metal mask opening pattern

Metal mask thickness: When $120 \mu\text{m}$
(Terminal opening ratio: 70%)
(Metal-part opening ratio: 100%)



PRECAUTIONS COMMON TO ADVANCED SERIES NARROW-PITCH CONNECTORS

■ Connector mounting

In case the connector is picked up by chucking during mounting, an excessive mounter chucking force may deform the molded or metal part of the connector. Consult us in advance if chucking is to be applied.

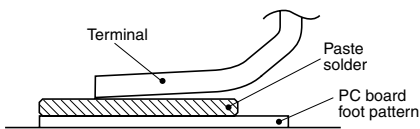
■ Soldering

1) Manual soldering.

- Due to the low profile, if an excessive amount of solder is applied to this product during manual soldering, the solder may creep up to near the contact points, or interference by solder may cause imperfect contact.
- Make sure that the soldering iron tip is heated within the temperature and time limits indicated in the specifications.
- Flux from the solder wire may adhere to the contact surfaces during soldering operations. After soldering, carefully check the contact surfaces and clean off any flux before use.
- Be aware that a load applied to the connector terminals while soldering may displace the contact.
- Thoroughly clean the iron tip.

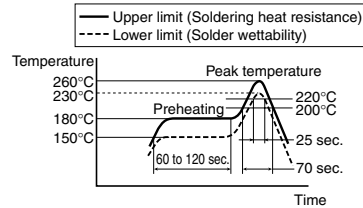
2) Reflow soldering

- Screen-printing is recommended for printing paste solder.
 - To determine the relationship between the screen opening area and the PC-board foot pattern area, refer to the diagrams in the recommended patterns for PC boards and metal masks. Make sure to use the terminal tip as a reference position when setting.
- Avoid an excessive amount of solder from being applied, otherwise, interference by the solder will cause an imperfect contact.



- Consult us when using a screen-printing thickness other than that recommended.
- Depending on the size of the connector being used, self alignment may not be possible. Accordingly, carefully position the terminal with the PC board pattern.
- The recommended reflow temperature profile is given in the figure below

Recommended reflow temperature profile

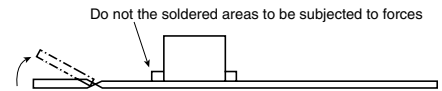


- The temperature is measured on the surface of the PC board near the connector terminal.
 - Some solder and flux types may cause serious solder creeping. Take the solder and flux characteristics into consideration when setting the reflow soldering conditions.
 - When performing reflow soldering on the back of the PC board after reflow soldering the connector, secure the connector using, for example, an adhesive (Double reflow soldering on the same side is possible)
- ### 3) Reworking on a soldered portion
- Finish reworking in one operation.
 - For reworking of the solder bridge, use a soldering iron with a flat tip. Do not add flux, otherwise, the flux may creep to the contact parts.
 - Use a soldering iron whose tip temperature is within the temperature range specified in the specifications.

■ **Do not drop the product or handle it carelessly. Otherwise, the terminals may become deformed due to excessive force or the solderability during reflow soldering may degrade.**

■ **Do not insert or remove the connector when it is not soldered. Also, forcibly applied external pressure on the terminals can weaken the adherence of the terminals to the molded part or cause the terminals to lose their evenness.**

■ **When cutting or bending the PC board after mounting the connector, be careful that the soldered sections are subjected to excessive forces.**



■ Notes when using a FPC.

- When the connector is soldered to an FPC board, during its insertion and removal procedures, forces may be applied to the terminals and cause the soldering to come off. It is recommended to use a reinforcement board on the backside of the FPC board to which the connector is being connected. Make sure that the reinforcing plate is larger than the outline of the recommended PC board pattern (Outline + approx. 1 mm). The reinforcing plate is made of glass epoxy or polyimide that is 0.2 to 0.3 mm thick. This connector employs a simple locking structure. However, the connector may come off depending on the size and weight of the FPC, layout and reaction force of FPC, or by drop impact. Make sure to fully check the equipment's condition. To prevent any problem with loose connectors, adopt measures to prevent the connector from coming off inside the equipment.

■ Other Notes

When coating the PC board after soldering the connector to prevent the deterioration of insulation, perform the coating in such a way so that the coating does not get on the connector. The connectors are not meant to be used for switching.

For other details, please verify with the product specification sheets.